CST150N03F N-Ch 30V Fast Switching MOSFETs

★ 100% EAS Guaranteed
★ Green Device Available
★ Super Low Gate Charge
★ Excellent CdV/dt effect decline
★ Advanced high cell density Trench technology

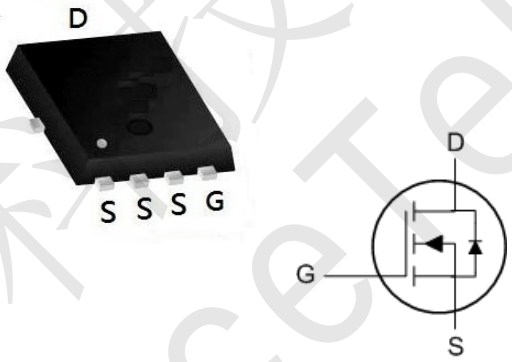
CST150N03F Product Summary

BVDSS	RDSON	ID
30V	1.5mΩ	150A

CST150N03F Description

The CST150N03F is the high cell density trenched N-ch MOSFETs, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.
The CST150N03F meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

CST150N03F PDFN5060-8L Pin Configuration



CST150N03F Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	30	V
V_{GS}	Gate-Source Voltage	±20	V
I_D@T_C=25℃	Continuous Drain Current, V_{GS} @ 10V[1,6]	150	A
I_D@T_C=100℃	Continuous Drain Current, V_{GS} @ 10V[1,6]	80	A
I_{DM}	Pulsed Drain Current[2]	450	A
EAS	Single Pulse Avalanche Energy[3]	580	mJ
I_{AS}	Avalanche Current	60	A
P_D@T_C=25℃	Total Power Dissipation[4]	87	W
T_{STG}	Storage Temperature Range	-55 to 150	℃
T_J	Operating Junction Temperature Range	-55 to 150	℃

CST150N03F Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-Ambient [1]	---	62	℃/W
$R_{\theta JC}$	Thermal Resistance Junction-Case[1]	---	2.1	℃/W

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CST150N03F Electrical characteristic (T_J = 25°C unless otherwise specified)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
Off characteristics						
BV_{DSS}	Drain to source breakdown voltage	V_{GS}=0V, I_D=250uA	30			V
ΔBV_{DSS} / ΔT_J	Breakdown voltage temperature coefficient	I_D=250uA, referenced to 25°C		0.02		V/°C
I_{DSS}	Drain to source leakage current	V_{DS}=30V, V_{GS}=0V			1	uA
		V_{DS}=24V, T_J=125°C			50	uA
I_{GSS}	Gate to source leakage current, forward	V_{GS}=20V, V_{DS}=0V			100	nA
	Gate to source leakage current, reverse	V_{GS}=-20V, V_{DS}=0V			-100	nA
On characteristics						
$V_{GS(TH)}$	Gate threshold voltage	V_{DS}=V_{GS}, I_D=250uA	1.2		2.4	V
$R_{DS(ON)}$	Drain to source on state resistance	V_{GS}=4.5V, I_D=30A,T_J=25°C		2.2	4.8	mΩ
		V_{GS}=10V, I_D=30A,T_J=25°C		1.5	2.9	mΩ
		V_{GS}=10V, I_D=30A,T_J=125°C		2.5		mΩ
G_{fs}	Forward transconductance	V_{DS}=5V, I_D=30A		73		S
Dynamic characteristics						
C_{iss}	Input capacitance	V_{GS}=0V, V_{DS}=15V, f=1MHz		6272		pF
C_{oss}	Output capacitance			1022		
C_{rss}	Reverse transfer capacitance			718		
$t_{d(on)}$	Turn on delay time	V_{DS}=15V, I_D=30A, R_G=4.7Ω, V_{GS}=10V (note 4,5)		20		ns
t_r	Rising time			58		
$t_{d(off)}$	Turn off delay time			158		
t_f	Fall time			77		
Q_g	Total gate charge	V_{DS}=24V, V_{GS}=10V, I_D=30A , I_G=5mA (note 4,5)		143		nC
Q_{gs}	Gate-source charge			17		
Q_{gd}	Gate-drain charge			43		
R_g	Gate resistance	V_{DS}=0V, Scan F mode		4.2		Ω

Source to drain diode ratings characteristics

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
I_S	Continuous source current	Integral reverse p-n Junction diode in the MOSFET			150	A
I_{SM}	Pulsed source current				440	A
V_{SD}	Diode forward voltage drop.	I_S=45A, V_{GS}=0V			1.4	V
t_{rr}	Reverse recovery time	I_S=30A, V_{GS}=0V, dI_F/dt=100A/us		26		ns
Q_{rr}	Reverse recovery charge			10		nC

※. Notes
1. Repeatitive rating : pulse width limited by junction temperature.
2. L =0.5mH, I_{AS} =48A, V_{DD}=30V, R_G=25Ω, Starting T_J = 25°C
3. I_{SD} ≤30A, di/dt = 100A/us, V_{DD} ≤ BV_{DSS}, Staring T_J =25°C
4. Pulse Test : Pulse Width ≤ 300us, duty cycle ≤ 2%.
5.

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Fig. 1. On-state characteristics

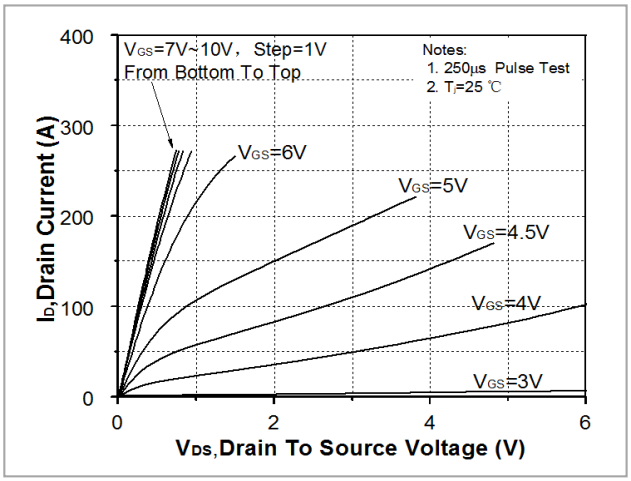

Fig. 2. Transfer Characteristics

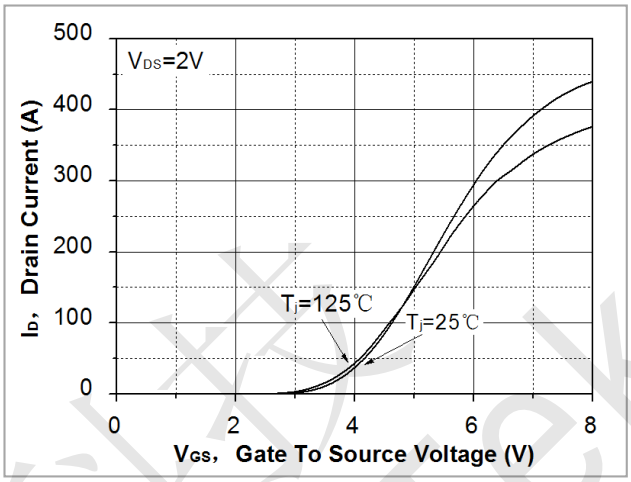

Fig. 3. On-resistance variation vs. drain current and gate voltage

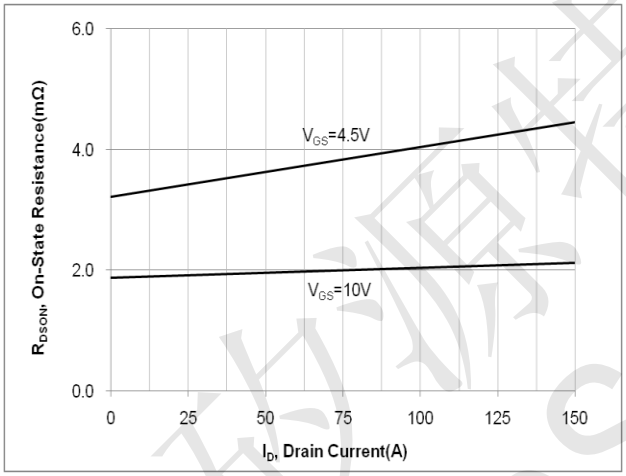

Fig. 4. On-state current vs. diode forward voltage

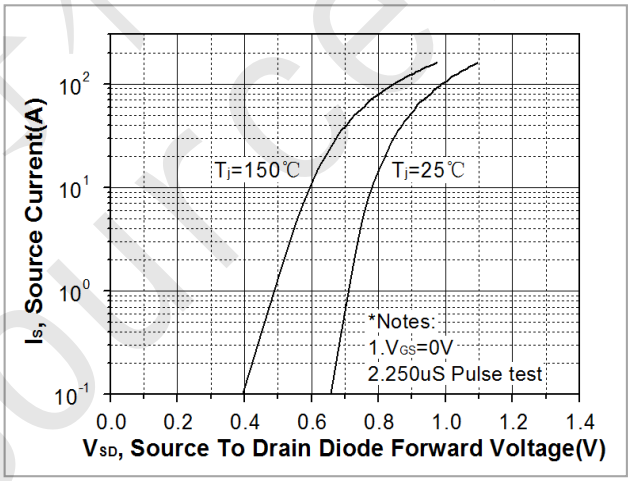

Fig 5. Breakdown voltage variation vs. junction temperature

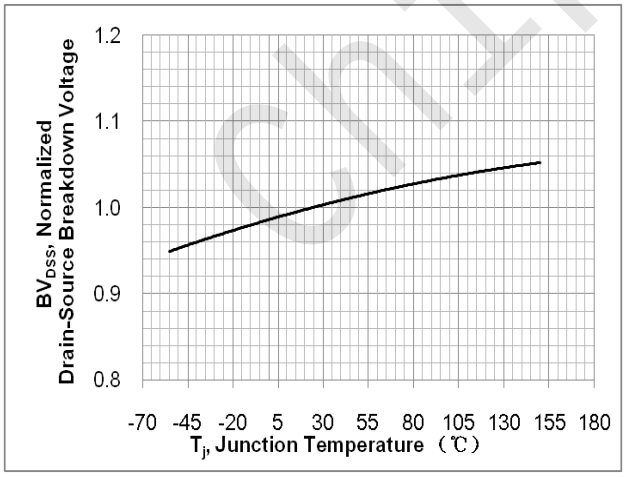

Fig. 6. On-resistance variation vs. junction temperature

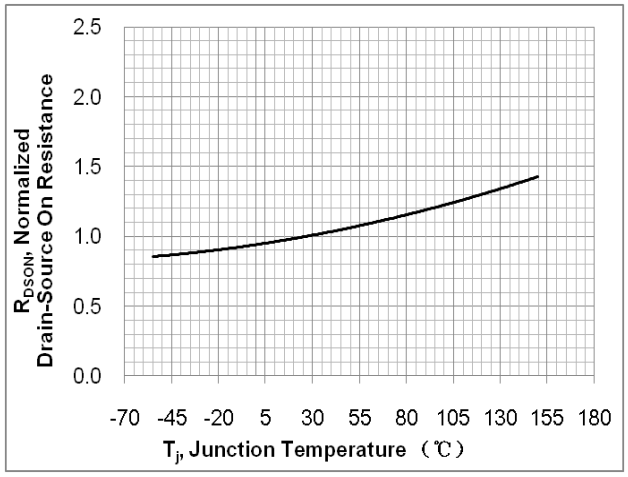

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Fig. 7. Gate charge characteristics

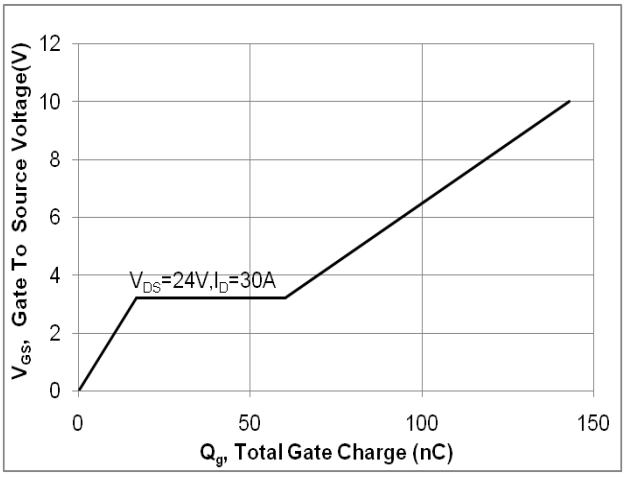


Fig. 8. Capacitance Characteristics

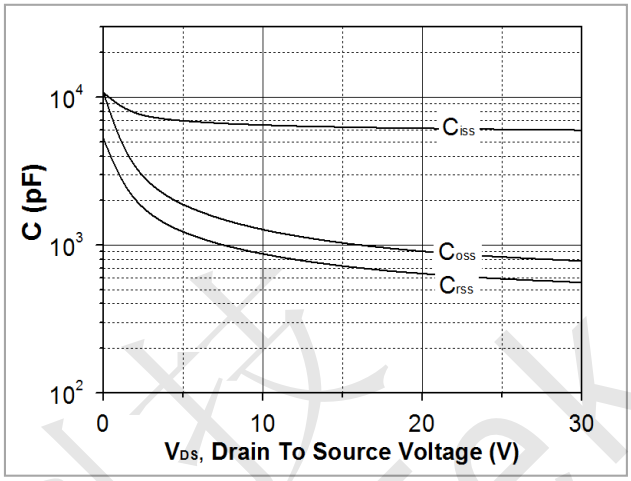


Fig. 9. Maximum safe operating area

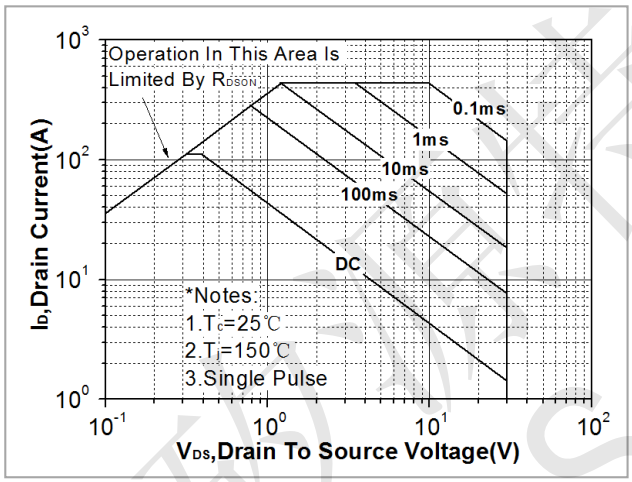


Fig. 10. Maximum drain current vs. case temperature

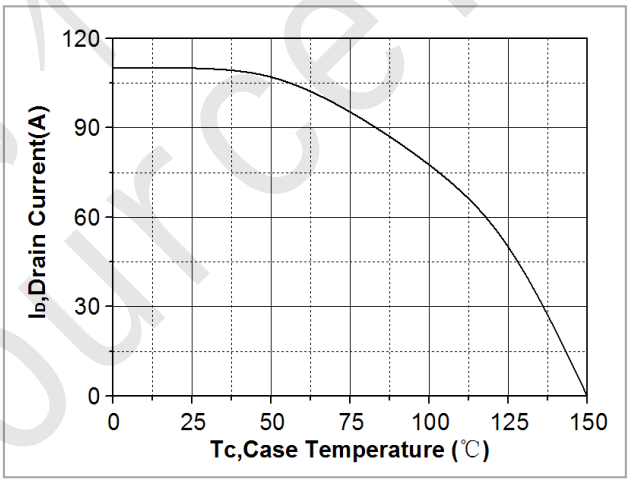
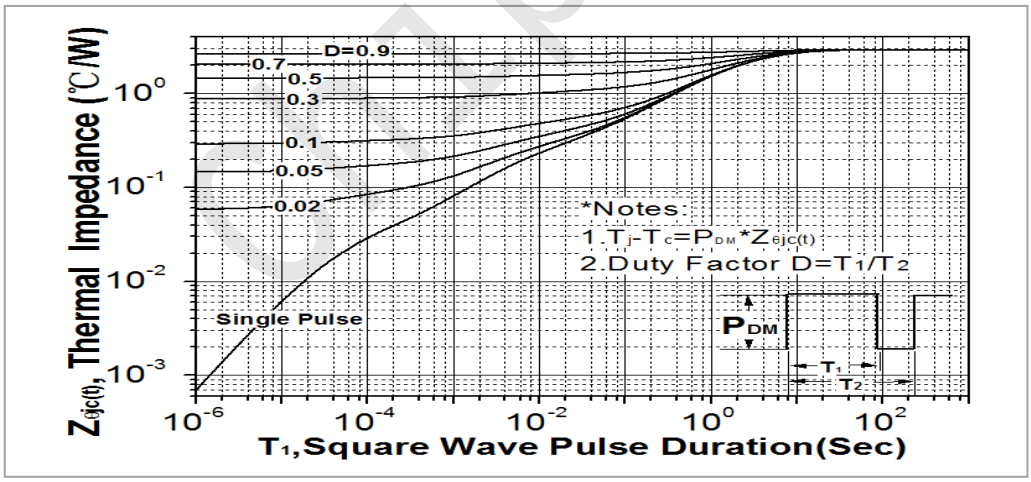


Fig. 11. Transient thermal response curve



CST150N03F Test Circuit

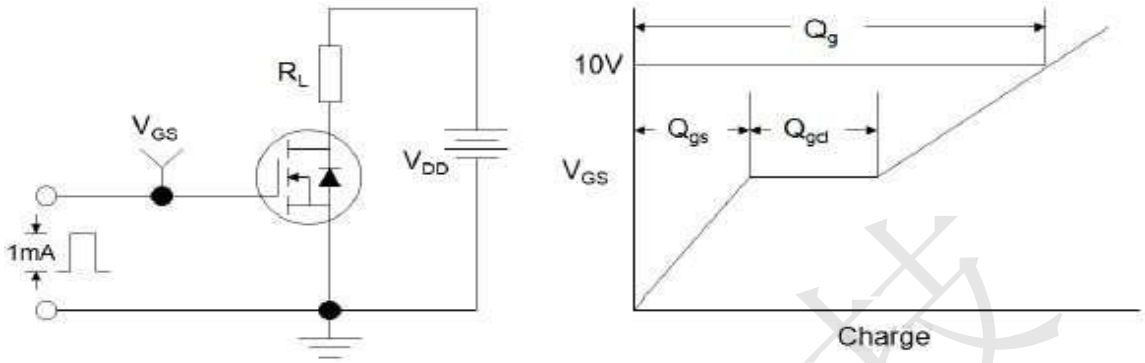


Figure1:Gate Charge Test Circuit & Waveform

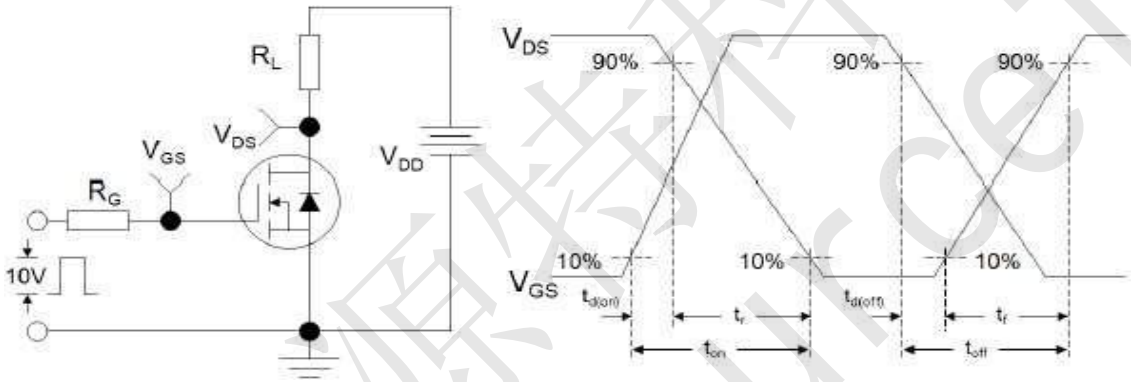


Figure 2: Resistive Switching Test Circuit & Waveforms

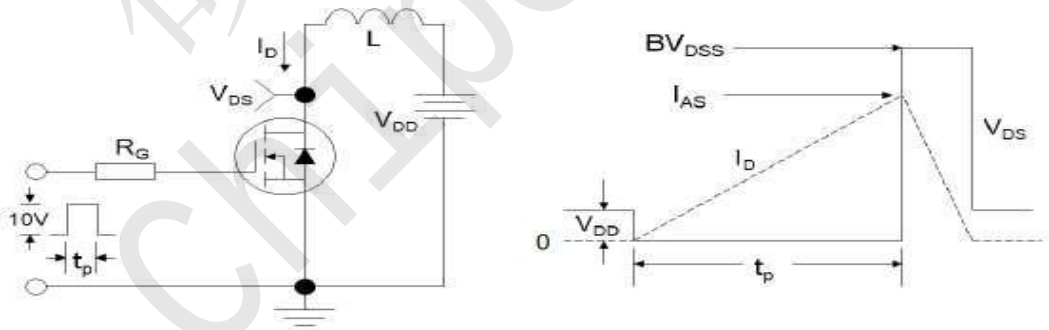
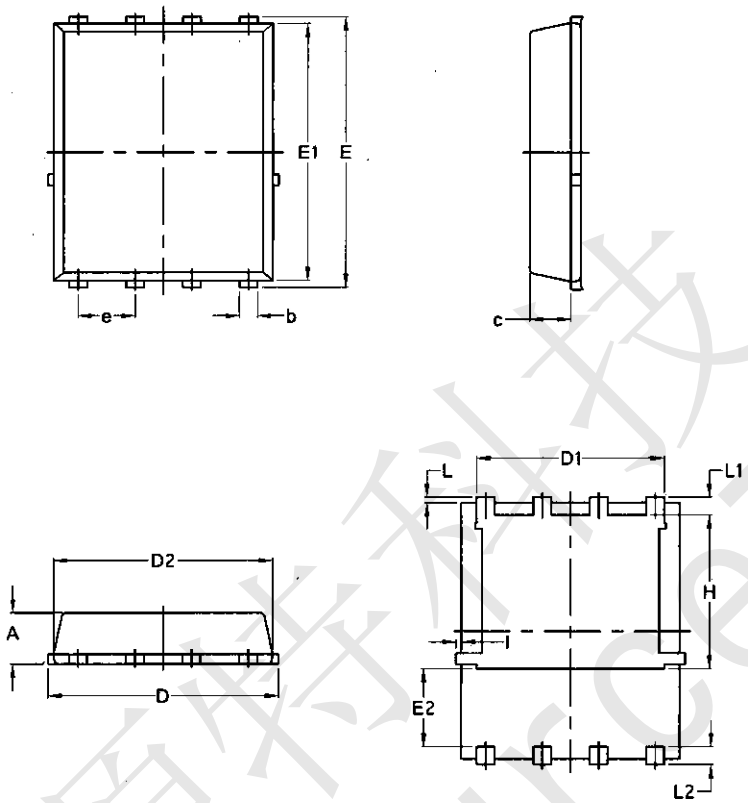


Figure 3:Unclamped Inductive Switching Test Circuit & Waveforms

CST150N03F Package Mechanical Data-PDFN5060-8L-JQ Single



Symbol	Common			
	mm		Inch	
	Mim	Max	Min	Max
A	1.03	1.17	0.0406	0.0461
b	0.34	0.48	0.0134	0.0189
c	0.824	0.0970	0.0324	0.082
D	4.80	5.40	0.1890	0.2126
D1	4.11	4.31	0.1618	0.1697
D2	4.80	5.00	0.1890	0.1969
E	5.95	6.15	0.2343	0.2421
E1	5.65	5.85	0.2224	0.2303
E2	1.60	/	0.0630	/
e	1.27 BSC		0.05 BSC	
L	0.05	0.25	0.0020	0.0098
L1	0.38	0.50	0.0150	0.0197
L2	0.38	0.50	0.0150	0.0197
H	3.30	3.50	0.1299	0.1378
I	/	0.18	/	0.0070